

PRINTED CIRCUIT BOARD ASSEMBLY AND METHOD**Abstract of the Disclosure**

A method of fabricating a printed circuit board assembly includes molding an array having a plurality of integrated circuits that are physically interconnected. Each integrated circuit has a molded body defining a lower surface. The integrated circuits have a plurality of electrical contacts on the bottom surface. The method includes singulating the array to form a plurality of separate integrated circuits, and at least a portion of the electrical contacts are cut. An organic solderability preservative is applied to the cut portion of the electrical contacts. Heat is applied to the integrated circuits to dry the circuits, and the integrated circuits are soldered to a printed circuit board by applying molten solder to remove the organic solderability preservative.